

200V N-Channel Power MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)TYP}	l _D
200V	9.2mΩ@10V	110A



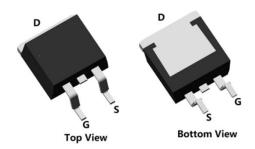
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

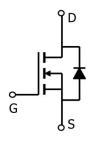
- Power switching application
- DC-DC Converter
- Power Management

Package

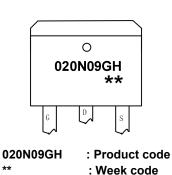


TO-263(1:G 2:D 3:S)

Circuit diagram



Marking



Order Information

Device	Package	Unit/Tape		
SP020N09GHTD	TO-263	800		

200V N-Channel Power MOSFET

Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	200	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current (Tc=25°C)	I _D	110	Α
Continuous Drain Current (Tc=100°ℂ)	I _D	73	Α
Pulsed Drain Current	I _{DM}	440	Α
Single Pulse Avalanche Energy ¹	Eas	1296	mJ
Power Dissipation (Tc=25°C)	P _D	270	W
Thermal Resistance Junction-to-Case	R _{θJC}	0.46	°C/W
Storage Temperature Range	T _{STG}	55 to 150	$^{\circ}$
Operating Junction Temperature Range	TJ	55 to 150	$^{\circ}$

Electrical characteristics (Ta=25°C, unless otherwise noted)

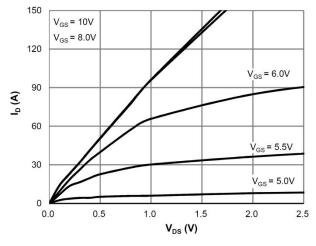
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Static Characteristics			1			
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	200	-	-	V
Drain Cut-Off Current	I _{DSS}	V _{DS} = 160V, V _{GS} = 0V	-	-	1	
Gate Leakage Current	Igss	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±0.1	uA
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2.0	3.0	4.0	V
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} = 10V, I _D = 20A	-	9.2	11.5	mΩ
Dynamic Characteristics						
Input Capacitance	C _{iss}		-	4183	-	
Output Capacitance	Coss	V _{DS} =100V, V _{GS} = 0V, f = 1.0MHz	-	437	-	pF
Reverse Transfer Capacitance	C _{rss}		-	12	-	
Total Gate Charge	Qg		-	48	-	nC
Gate-Source Charge	Qgs	V _{DS} =100V , VGS=10V , ID=20A	-	31	-	
Gate-Drain Charge	Q_{gd}		-	11	-	
Switching Characteristics	·					
Turn-On Delay Time	t _{d(on)}		-	13	-	
Rise Time	t _r	$V_{GS} = 10V, V_{DS} = 100V, R_L = 3.5\Omega$	-	25	-	20
Turn-Off Delay Time	t _{d(off)}	$R_G = 6.0\Omega$	-	31	-	nS
Fall Time	t _f		-	25	-	
Drain-Source Body Diode Characteri	stics					
Source-Drain Diode Forward Voltage	V _{SD}	V _{GS} =0V , I _S =1A , T _J =25°C	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	110	А
Reverse Recovery Time	Trr	l _s =140A, di/dt=100A/us, T _J =25℃	_	165	-	nS
Reverse Recovery Charge	Qrr	18-140A, di/dt-100A/ds, 1j=25 C		521	-	nC

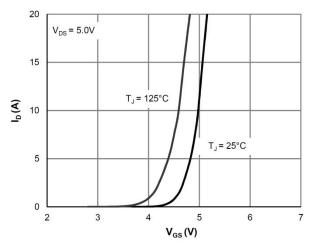
Note:

1. The EAS test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25 Ω



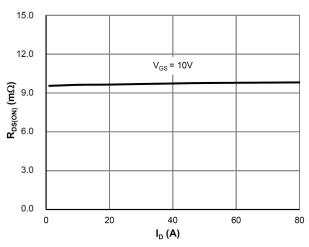
Typical Characteristics

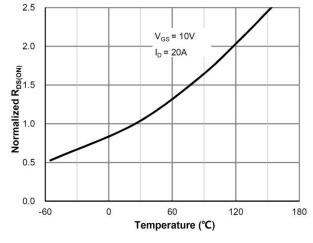






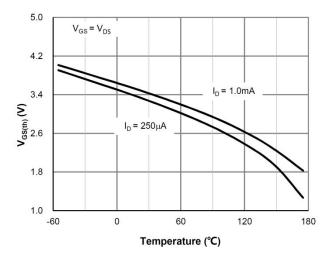


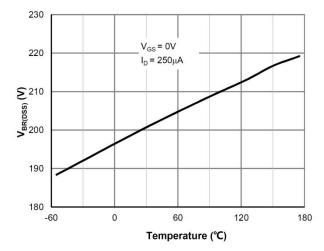




R_{DS(ON)} vs. Drain Current

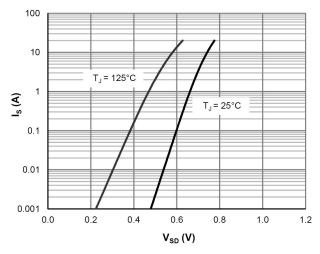
 $R_{\mathrm{DS(ON)}}$ vs. Junction Temperature

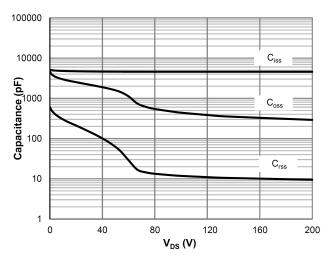




 $V_{\text{GS(th)}}$ vs. Junction Temperature

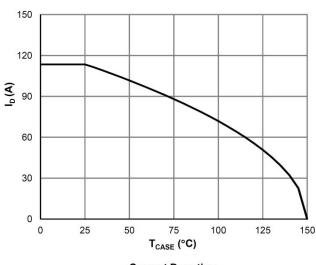
 $\mathbf{V}_{\text{BR}(\text{DSS})}$ vs. Junction Temperature

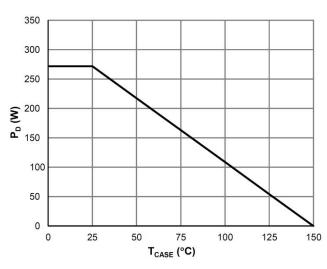




Body-Diode Characteristics

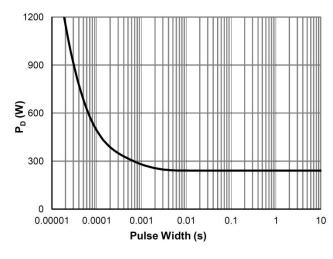


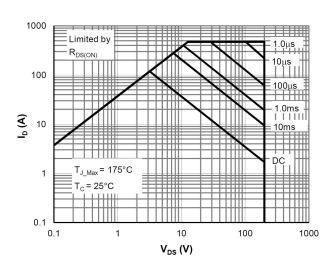




Current De-rating

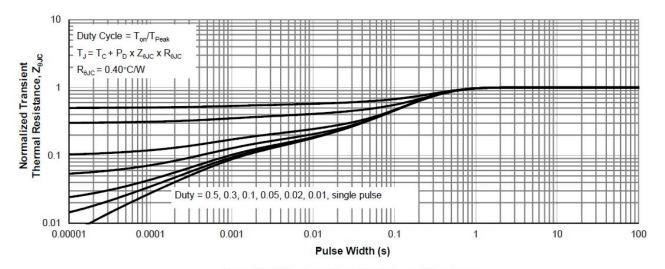
Power De-rating





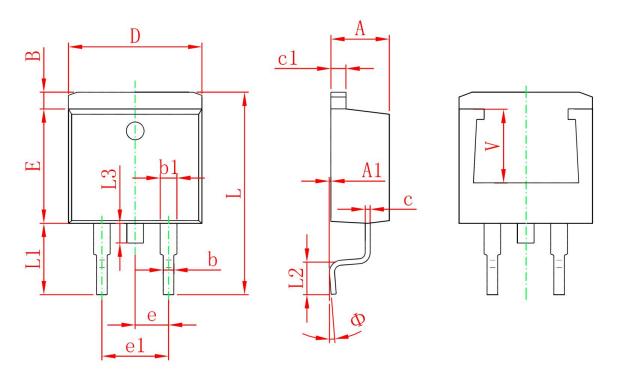
Single Pulse Power Rating, Junction-to-Case

Maximum Safe Operating Area



Normalized Maximum Transient Thermal Impedance

TO-263 Package Information



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.120	1.420	0.044	0.056	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204	
L	14.940	15.500	0.588	0.610	
L1	4.950	5.450	0.195	0.215	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
Ф	0°	8°	0°	8°	
V	5.600	5.600 REF. 0.220 REF.		REF.	